

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT2619770

SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>KAZUYUKI TAMURA</td> <td>11/19/2013</td> </tr> <tr> <td>TAKASHI AKUTSU</td> <td>10/29/2013</td> </tr> <tr> <td>YUKI ETO</td> <td>10/29/2013</td> </tr> <tr> <td>TOMOHIDE HUKUZAKI</td> <td>10/22/2013</td> </tr> </tbody> </table>		Name	Execution Date	KAZUYUKI TAMURA	11/19/2013	TAKASHI AKUTSU	10/29/2013	YUKI ETO	10/29/2013	TOMOHIDE HUKUZAKI	10/22/2013
Name	Execution Date										
KAZUYUKI TAMURA	11/19/2013										
TAKASHI AKUTSU	10/29/2013										
YUKI ETO	10/29/2013										
TOMOHIDE HUKUZAKI	10/22/2013										
RECEIVING PARTY DATA											
<table border="1"> <tr> <td>Name:</td> <td>LINTEC CORPORATION</td> </tr> <tr> <td>Street Address:</td> <td>23-23 HONCHO, ITABASHI-KU</td> </tr> <tr> <td>City:</td> <td>TOKYO</td> </tr> <tr> <td>State/Country:</td> <td>JAPAN</td> </tr> <tr> <td>Postal Code:</td> <td>173-0001</td> </tr> </table>		Name:	LINTEC CORPORATION	Street Address:	23-23 HONCHO, ITABASHI-KU	City:	TOKYO	State/Country:	JAPAN	Postal Code:	173-0001
Name:	LINTEC CORPORATION										
Street Address:	23-23 HONCHO, ITABASHI-KU										
City:	TOKYO										
State/Country:	JAPAN										
Postal Code:	173-0001										
<table border="1"> <tr> <td>Name:</td> <td>ARAKAWA CHEMICAL INDUSTRIES, LTD.</td> </tr> <tr> <td>Street Address:</td> <td>3-7 HIRANOMACHI 1-CHOME, CHUO-KU, OSAKA-SHI</td> </tr> <tr> <td>City:</td> <td>OSAKA</td> </tr> <tr> <td>State/Country:</td> <td>JAPAN</td> </tr> <tr> <td>Postal Code:</td> <td>541-0046</td> </tr> </table>		Name:	ARAKAWA CHEMICAL INDUSTRIES, LTD.	Street Address:	3-7 HIRANOMACHI 1-CHOME, CHUO-KU, OSAKA-SHI	City:	OSAKA	State/Country:	JAPAN	Postal Code:	541-0046
Name:	ARAKAWA CHEMICAL INDUSTRIES, LTD.										
Street Address:	3-7 HIRANOMACHI 1-CHOME, CHUO-KU, OSAKA-SHI										
City:	OSAKA										
State/Country:	JAPAN										
Postal Code:	541-0046										
PROPERTY NUMBERS Total: 1											
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14005577</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14005577						
Property Type	Number										
Application Number:	14005577										
CORRESPONDENCE DATA											
Fax Number:	(202)331-3838										
Phone:	202-331-8777										
Email:	docketing@cahnsamuels.com										
<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>											
Correspondent Name:	CAHN & SAMUELS LLP										
Address Line 1:	1100 17TH STREET NW										

OP \$40.00 14005577

Address Line 2:	SUITE 401
Address Line 4:	WASHINGTON, DISTRICT OF COLUMBIA 20036

ATTORNEY DOCKET NUMBER:	919.0031
-------------------------	----------

NAME OF SUBMITTER:	WARREN ZITLAU
--------------------	---------------

Signature:	/Warren Zitlau/
------------	-----------------

Date:	11/19/2013
-------	------------

Total Attachments: 2 source=ExecutedAssignment#page1.tif source=ExecutedAssignment#page2.tif
--

ASSIGNMENT OF PATENT APPLICATION

FOR GOOD AND VALUABLE CONSIDERATION,

I, the undersigned hereby agrees to assign for good and valuable consideration, receipt of which is hereby expressly acknowledged, and do hereby sell, assign and transfer unto

LINTEC Corporation of 23-23 Honcho, Itabashi-ku, Tokyo 173-0001, Japan

Arakawa Chemical Industries, Ltd. of 3-7, Hiranomachi 1-chome, Chuo-ku, Osaka-shi, Osaka 541-0046, Japan

corporations organized under the laws of JAPAN, and its successors, assigns and legal representatives, the entire right, title and interest, for all countries in and to certain inventions relating to

BASE FILM AND PRESSURE-SENSITIVE ADHESIVE SHEET PROVIDED THEREWITH

described in an application for Letters Patent of the United States, identified as Attorney Docket No. 919,0031, at Cahn & Samuels, LLP, 1100 17th Street N.W., Suite 401, Washington, DC 20036-4650 and filed on September 17, 2013, as Application Serial No. 14/005,577, and the invention(s) and improvement(s) set forth therein, and any and all continuations, continuations-in-part, divisionals, and renewals of and substitutes for said application for said Letters Patent, and all the rights and privileges under any and all Letters Patent that may be granted therefor in any country, and any reissues, or reexaminations, or extensions of said Letters Patent. I request that any and all Letters Patent for said inventions be issued to said Assignee, its successors, assigns and legal representatives, or to such nominees as it may designate.

I agree that, when requested, I will, without charge to said Assignee but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable or convenient for securing and maintaining patents for said inventions in any and all countries and for vesting title thereto in said Assignee, its successors, assigns and legal representatives or nominees.

I authorize and empower the said Assignee, its successors, assigns and legal representatives or nominees, to invoke and claim for any application for patent or other form of protection for said inventions filed by it or them, the benefit of the right of priority provided by the International Convention for the Protection of Industrial Property, as amended, or by any convention which may henceforth be substituted for it, and to invoke and claim such right of priority without further written or oral authorization from me.

I hereby consent that a copy of this assignment shall be deemed a full legal and formal equivalent of any assignment, consent to file or like document which may be required in any country for any purpose and more particularly in proof of the right of the said Assignee or nominee to claim the aforesaid benefit of the right of priority provided by the International convention which may henceforth be substituted for it.

I hereby authorize Warren A. Zitlau, attorney for Assignee, to insert the filing date and Serial number into the first paragraph of this assignment, after the application for Letters Patent has been filed, and the U.S. Patent Office has assigned such application a Serial Number.

I covenant with said Assignee, its successors, assigns and legal representatives, that the rights and property herein conveyed are free and clear of any encumbrance, and that I have full right to convey the same as herein expressed.

IN WITNESS WHEREOF, I have hereunto signed my name on the day and year set forth below.

Kazuyuki Tamura  
Inventor's Signature  
Kazuyuki TAMURA  
Inventor's Printed Name

November 19, 2013  
DATE

Takashi AKUTSU  
Inventor's Signature  
Takashi AKUTSU  
Inventor's Printed Name

October 29, 2013  
DATE

Yuki ETO

Inventor's Signature

Yuki ETO

Inventor's Printed Name

October 29, 2013

DATE

Tomohide HUKUZAKI

Inventor's Signature

Tomohide HUKUZAKI

Inventor's Printed Name

October 22, 2013

DATE